



TowerJazz

Line of Business

Semiconductor foundry

Established

1993

Executive Management

Mr. Russell Ellwanger
CEO

Mr. Itzhak Edrei
Executive Vice President
of Business Groups

Mr. Chuck Fox
Senior VP, Worldwide Sales
& Corporate Marketing

Mr. Oren Shirazi
CFO, VP of Finance

Mr. Ephie Koltin
Senior Vice President,
Worldwide Operations

Mr. Rafi Mor
Senior Vice President
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Mrs. Dalit Dahan
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TOWERJAZZ

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Tower Semiconductor and Jazz Technologies merged in September 2008 in a stock for stock transaction. In November 2009, the combined companies officially launched as TowerJazz.

Tower Semiconductor was founded in 1993, with the acquisition of National Semiconductor's 150-mm wafer fabrication facility. Tower became a public company in 1994 and shares are traded on NASDAQ (TSEM) and Tel Aviv Stock Exchange (TSEM).

Jazz Semiconductor was formed in 2002 as a spinoff of Conexant Systems, a fabless semiconductor company that spun-off from Rockwell



Semiconductor in 1999. Jazz inherited the Newport Beach, California 200mm fabrication facility and the company's legacy.

Technology Overview

TowerJazz offers wafer foundry services providing the widest range of customizable CMOS specialty processes and proven design enablement tools for the manufacture of optimized integrated circuits (ICs). Our process technologies with geometries ranging from 1.0- to 0.13-micron include: SiGe, BiCMOS, Mixed-Signal & RFCMOS, CMOS Image Sensor (CIS), Power Management (BCD), Digital CMOS, Embedded Non-Volatile Memory (NVM) as well as MEMS capabilities integrated with CMOS. These modular processes are tailored to meet our customers' precise specifications for the most cost-effective and versatile solutions. We offer

a proven design enablement platform for unprecedented accuracy and first-time success including silicon verified and scalable device models and robust physical design tools.

We are well recognized for our SiGe, BiCMOS and RFCMOS. We are the only pure play foundry with multi-fab SiGe capacity for the manufacture of high performance analog (HPA) products. Our SiGe process is often competitive with GaAs, offering as much as 40% lower die cost.

We have industry leading, Bipolar-CMOS-DMOS (BCD) processes for use in complex power management chips and a leading CMOS Image Sensor (CIS) technology to meet the growing demand for optical sensors used in consumer, industrial, medical and automotive applications. We offer MEMS solutions coupled with high volume 200mm CMOS manufacturing to address complex wireless and consumer electronics markets. We provide on-shore foundry services to the Aerospace and Defense industry for Large Die, ROICs and millimeter wave applications. In addition, we offer Transfer Optimization and Process Services (TOPS) to IDMs and fables companies to expand capacity or provide second sourcing. All of these process technologies are manufactured on either 150mm or 200millimeter wafers in our world-class fabrication facilities which have achieved quality certifications for Environmental Management, Health & Safety, Information Security, and Automotive standards.